

100A 650V Trench Fieldstop IGBT with anti-parallel diode SRE100N065FSUD8
General Description

The SRE100N065FSUD8 is a Field Stop Trench IGBT with anti-parallel diode, which offers ultra-low switching losses, high energy efficiency for switching applications such as PFC, Power Supply, Inverter, etc.

The SRE100N065FSUD8 package is TO-247-4.

Features

- High Breakdown Voltage to 650V
- Advanced Trench Fieldstop technology
 - Ultra low E_{off}
 - High Ruggedness, Temperature Stability
 - Easy Parallel Switching Capability due to Positive Temperature Coefficient in $V_{CE(SAT)}$
- LOW $V_{CE(SAT)}$
- Enhanced Avalanche Capability
- Non-Automotive Qualified

Application

- Inverter
- Uninterruptible power supplies
- PFC application
- Converter with high switching frequency

Ordering Information

SRE100N065FSUD8□□-□

Circuit Type _____
 Package _____
 T4: TO-247-4

G: Green
 Blank: Tube
 TR: Tape & Reel

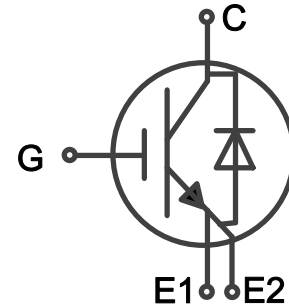
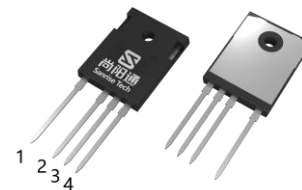
Symbol


Figure 1 Symbol of SRE100N065FSUD8

Package Type


TO-247-4

Figure 2 Package Type of SRE100N065FSUD8

Package	Part Number	Marking ID	Packing Type
TO-247-4	SRE100N065FSUD8T4-G	SRE100N065FSUD8T4G	Tube

100A 650V Trench Fieldstop IGBT with anti-parallel diode SRE100N065FSUD8
Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Collector-emitter Voltage		V_{CES}	650	V
Gate-emitter Voltage		V_{GES}	± 20	V
Transient Gate-emitter Voltage			± 30	V
Continuous Collector Current	$T_C=25^\circ\text{C}$	I_C	125	A
	$T_C=100^\circ\text{C}$		100	
Pulsed Collector Current, Limited by T_{Jmax}		I_{CM}	400	A
Diode Continuous Collector Current	$T_C=25^\circ\text{C}$	I_F	100	A
	$T_C=100^\circ\text{C}$		80	
Diode Pulsed Current, Limited by T_{Jmax}		I_{FM}	320	A
Power Dissipation	$T_C=25^\circ\text{C}$	P_{tot}	395	W
	$T_C=100^\circ\text{C}$		197	
Operating Junction Temperature Range		T_J	$-40\sim 175^{(1)}$	$^\circ\text{C}$
Storage Temperature Range		T_{STG}	$-55 \sim 150$	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

 1. Reliability testing conducted at $T_j=175^\circ\text{C}$.

Thermal Resistance

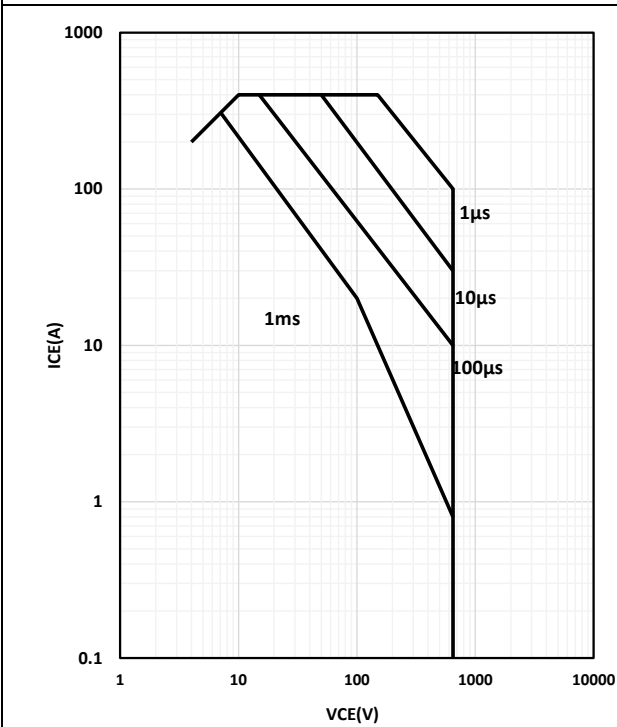
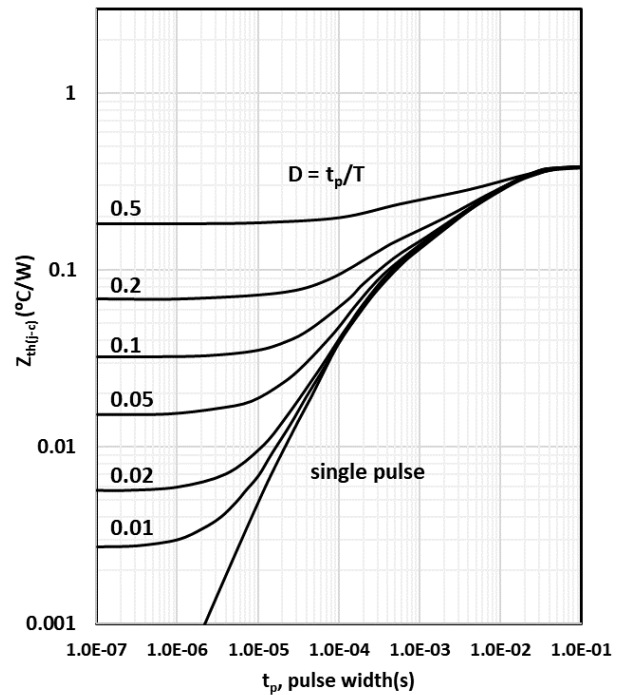
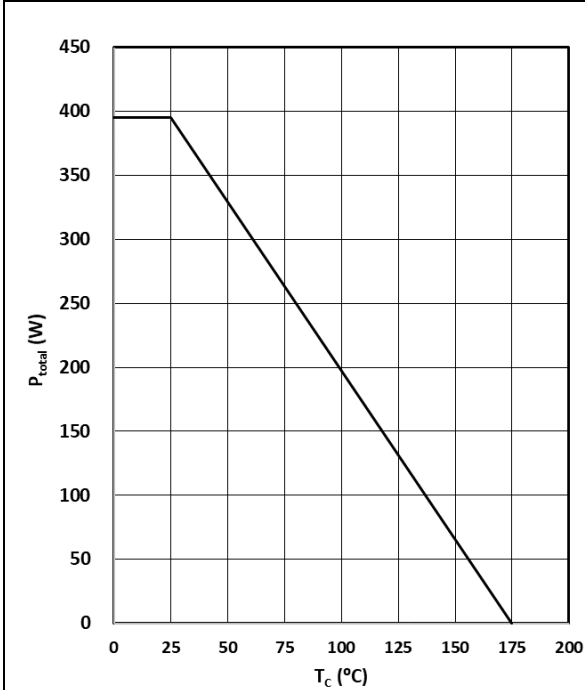
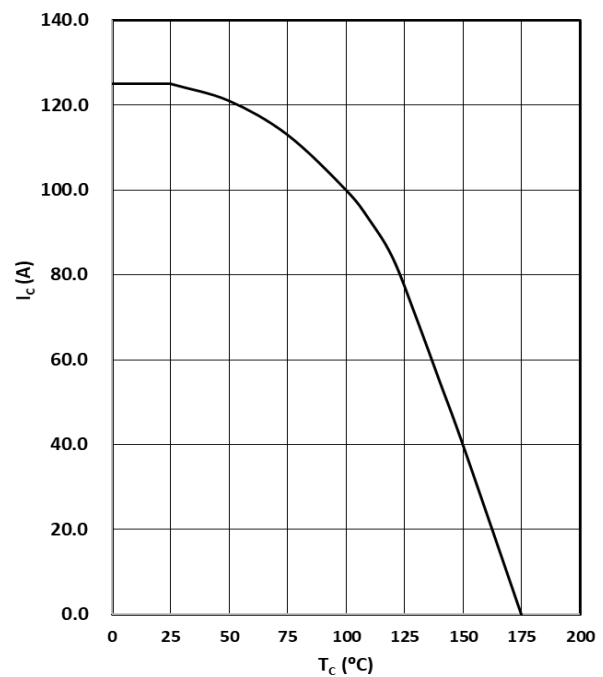
Parameter	Symbol	Min.	Typ.	Max.	Unit
IGBT Thermal Resistance, Junction-to-Case	R_{thJC}	-	-	0.38	$^\circ\text{C}/\text{W}$
Diode Thermal Resistance, Junction-to-Case	R_{thJC}	-	-	0.45	
Thermal Resistance, Junction-to-Ambient	R_{thJA}	-	-	40	

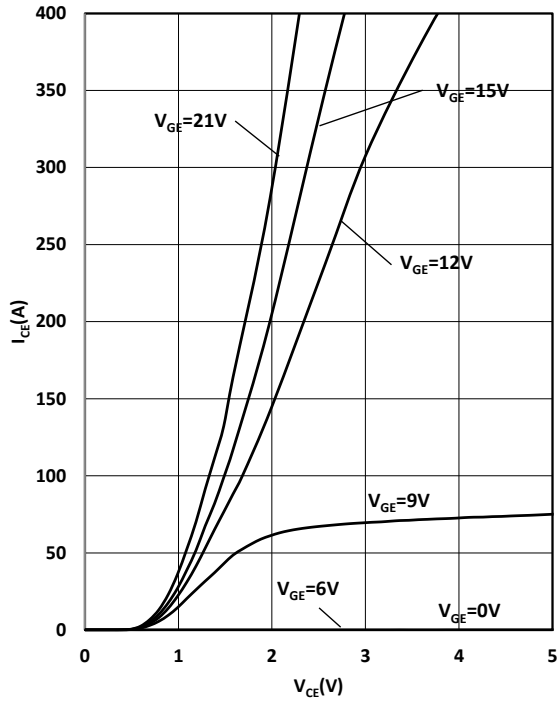
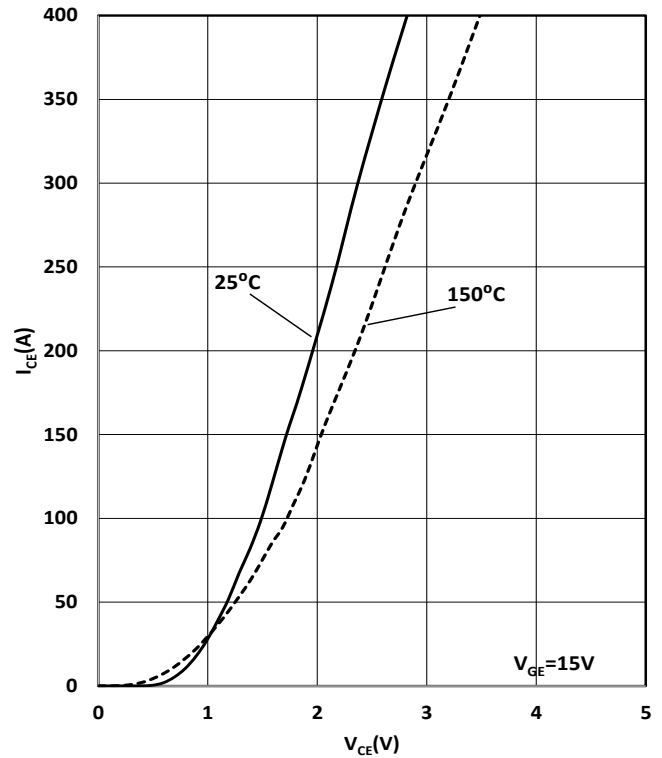
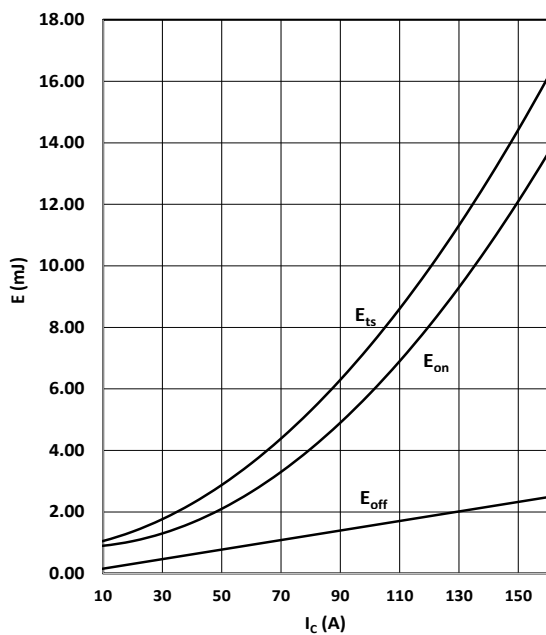
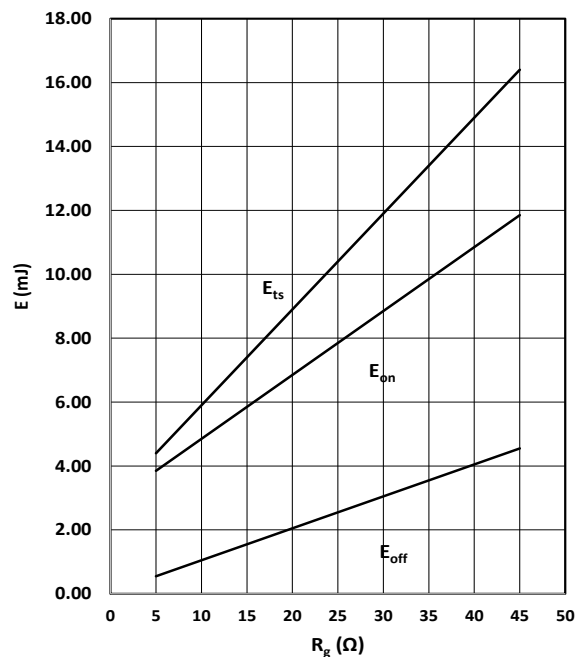
100A 650V Trench Fieldstop IGBT with anti-parallel diode SRE100N065FSUD8
Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

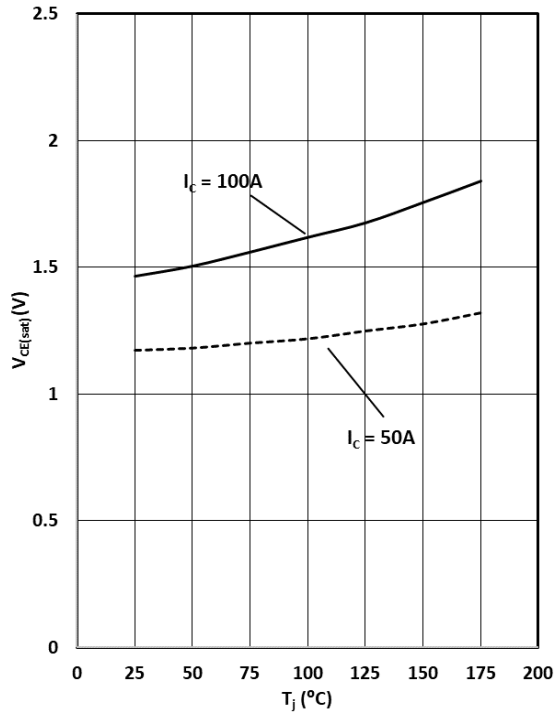
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Statistic Characteristics							
Collector-emitter Breakdown Voltage	BV_{CES}	$V_{GE}=0V, I_C=250\mu A$	650			V	
Gate Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=250\mu A$	4.0	4.8	5.6	V	
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE}=15V, I_C=100A, T_J=25^\circ\text{C}$		1.46	2.0	V	
		$I_C=100A, T_J=125^\circ\text{C}$		1.68		V	
		$I_C=100A, T_J=175^\circ\text{C}$		1.83		V	
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE}=650V, V_{GE}=0V, T_J=25^\circ\text{C}$		0.1	40	μA	
		$T_J=175^\circ\text{C}$			1	mA	
Gate-emitter Leakage Current	Forward	$I_{GESF}, V_{GE}=20V, V_{CE}=0V$			100	nA	
	Reverse	$I_{GESR}, V_{GE}=-20V, V_{CE}=0V$			-100	nA	
Dynamic Characteristics							
Input Capacitance	C_{IES}	$V_{CE}=25V, V_{GE}=0V, f=1\text{ MHz}$		3750		pF	
Output Capacitance	C_{OES}			350			
Reverse Transfer Capacitance	C_{RES}			40			
Gate Resistance	R_G	$f=1\text{ MHz, Open Drain}$		1.7		Ω	
Turn-on Delay Time	$t_{d(on)}$	$T_J=25^\circ\text{C}$ $V_{CC}=400V, I_C=100A$ $R_G=15\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		50		ns	
Rise Time	t_r			110		ns	
Turn-off Delay Time	$t_{d(off)}$			300		ns	
Fall Time	t_f			68		ns	
Turn-on energy	E_{on}			5.85		mJ	
Turn-off energy	E_{off}			1.55		mJ	
Total switching energy	E_{ts}			7.4		mJ	
Turn-on Delay Time	$t_{d(on)}$		$T_J=150^\circ\text{C}$ $V_{CC}=400V, I_C=100A$ $R_G=15\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		45		ns
Rise Time	t_r				120		ns
Turn-off Delay Time	$t_{d(off)}$				395		ns
Fall Time	t_f			83		ns	
Turn-on energy	E_{on}			7.85		mJ	
Turn-off energy	E_{off}			2.55		mJ	
Total switching energy	E_{ts}			10.4		mJ	
Gate to Emitter Charge	Q_{GE}	$V_{CC}=400V, I_C=100A, V_{GE}=0\text{ to }15V$			65		nC
Gate to Collector Charge	Q_{GC}			89			
Gate Charge Total	Q_G			215			

100A 650V Trench Fieldstop IGBT with anti-parallel diode SRE100N065FSUD8

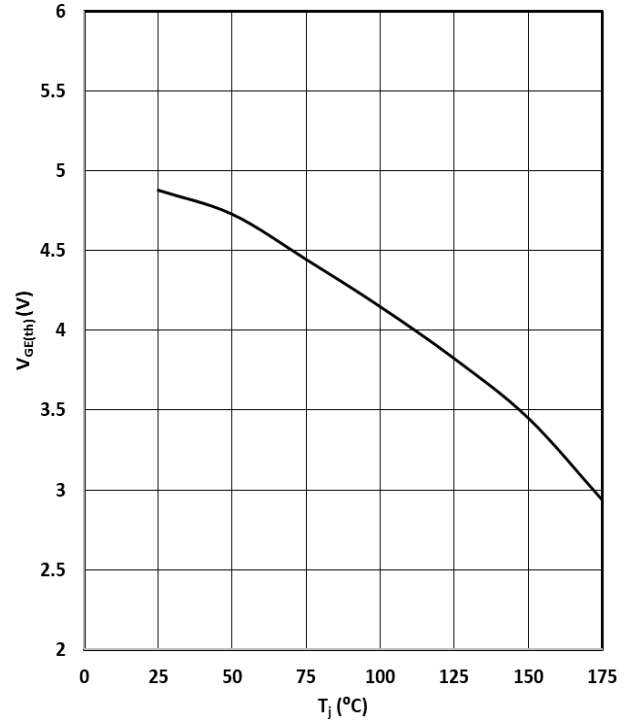
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Reverse Diode Characteristics						
Diode Forward Voltage	V_F	$I_F=50A$ $T_J=25^{\circ}C$		1.36	1.7	V
		$I_F=50A$ $T_J=125^{\circ}C$		1.11		
		$I_F=50A$ $T_J=175^{\circ}C$		1.01		
		$I_F=100A$ $T_J=25^{\circ}C$		1.58	1.9	
		$I_F=100A$ $T_J=125^{\circ}C$		1.46		
		$I_F=100A$ $T_J=175^{\circ}C$		1.38		
Reverse Recovery Time	t_{rr}	$T_J=25^{\circ}C$		125		ns
Reverse Recovery Charge	Q_{rr}	$V_R=400V, I_F=100A$		1084		nC
Peak Reverse Recovery Current	I_{rrm}	$dI_F/dt=700A/\mu s$		18.5		A

100A 650V Trench Fieldstop IGBT with anti-parallel diode SRE100N065FSUD8
Typical Performance Characteristics
Figure 3: IGBT FBSOA

 $I_C = f(V_{CE}); V_{GE} \geq 15/0V; T_j \leq 175^\circ C$
Figure 4: IGBT transient thermal impedance

 $R_{th(j-c)} = f(t_p); \text{ duty cycle: } D = t_p/T$
Figure 5: Power dissipation

 $P_{tot} = f(T_c);$
Figure 6: Collector current vs. temperature

 $I_C = f(T_c); V_{GE} \geq 15V; T_j \leq 175^\circ C$

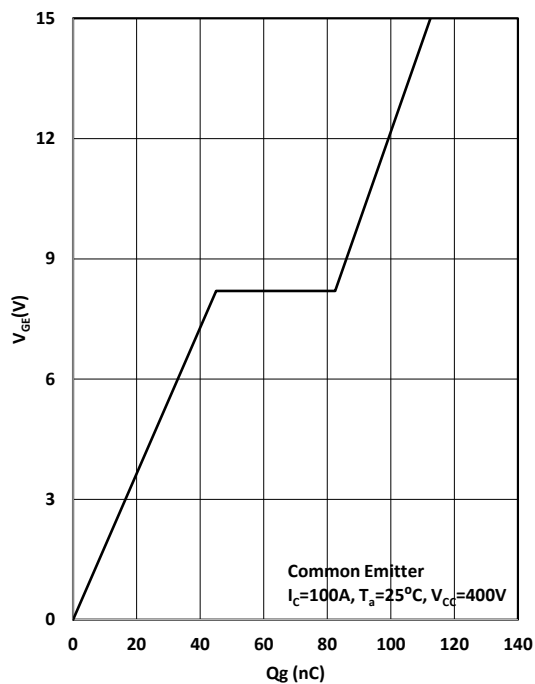
100A 650V Trench Fieldstop IGBT with anti-parallel diode SRE100N065FSUD8
Figure 7: Typical Output Characteristics

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GE}$
Figure 8: Typical transfer characteristic

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C vs } 150^\circ\text{C}$
Figure 9: Typical switching energy losses as a function of collector current

 $E = f(I_C); V_{CE} = 400\text{V}; T_j = 25^\circ\text{C}; R_G = 15\Omega$
Figure 10: Typical switching energy losses as a function of gate resistor

 $E = f(R_G); V_{CE} = 400\text{V}; T_j = 25^\circ\text{C}; I_C = 100\text{A}$

100A 650V Trench Fieldstop IGBT with anti-parallel diode SRE100N065FSUD8
Figure 11: Typical collector-emitter saturation voltage as a function of junction temperature


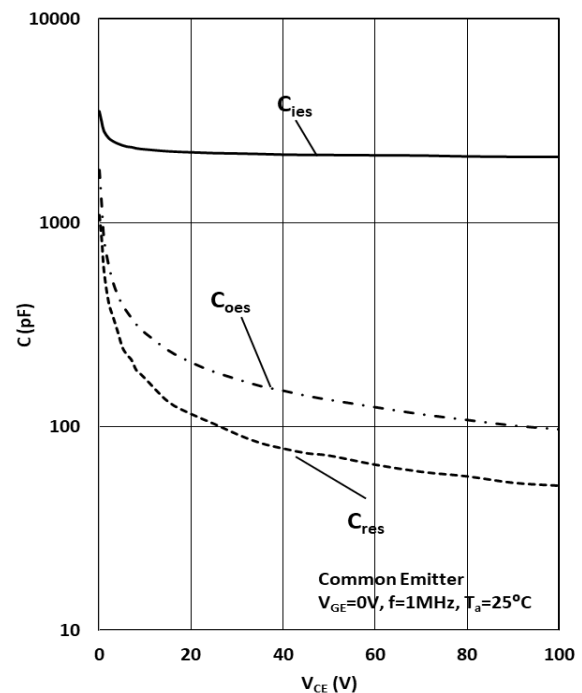
$$V_{CE} = f(T_j); V_{GE} = 15V$$

Figure 12: Gate-emitter threshold voltage as a function of junction temperature


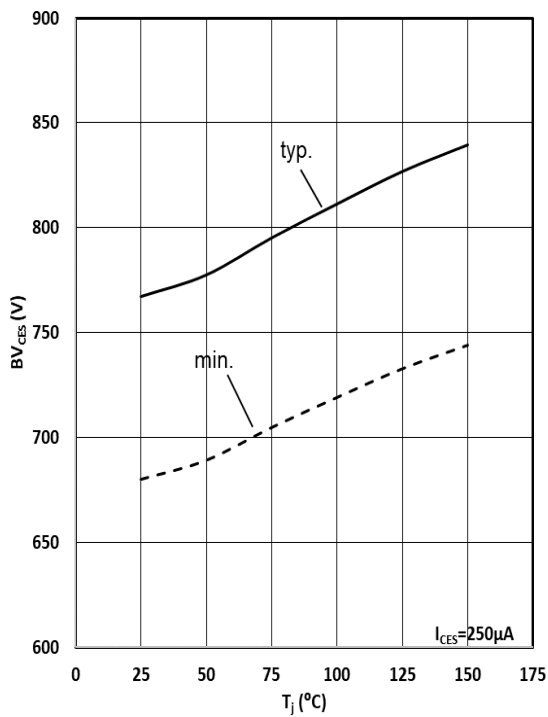
$$V_{GE} = f(T_j); I_{CE} = 250\mu A$$

Figure 13: Typical Gate Charge


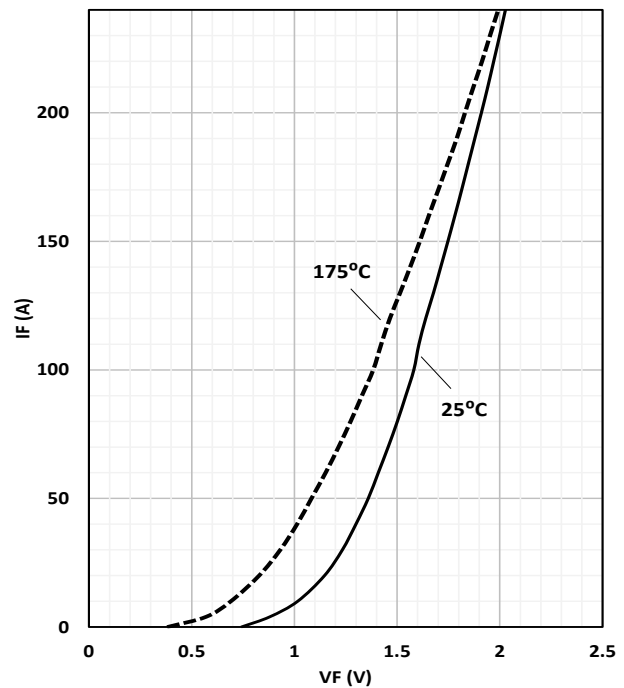
$$V_{GE} = f(Q_{gate}); I_C = 100A$$

Figure 14: Typical Capacitances


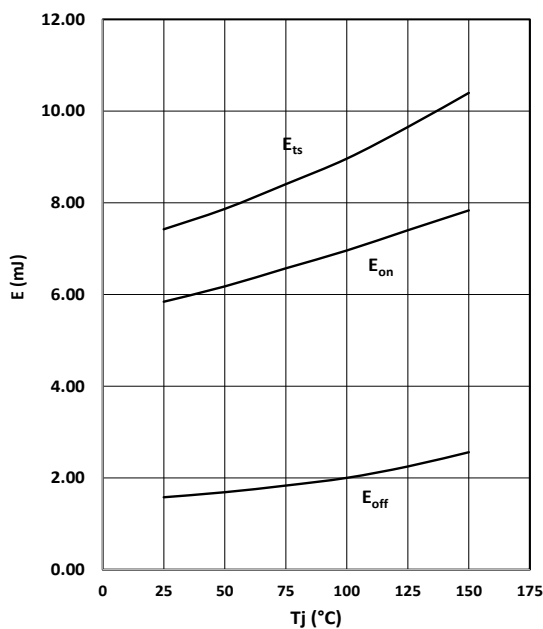
$$C = f(V_{CE}); V_{GE} = 0; f = 1MHz$$

100A 650V Trench Fieldstop IGBT with anti-parallel diode SRE100N065FSUD8
Figure 15: Collector-emitter Breakdown Voltage vs. temperature


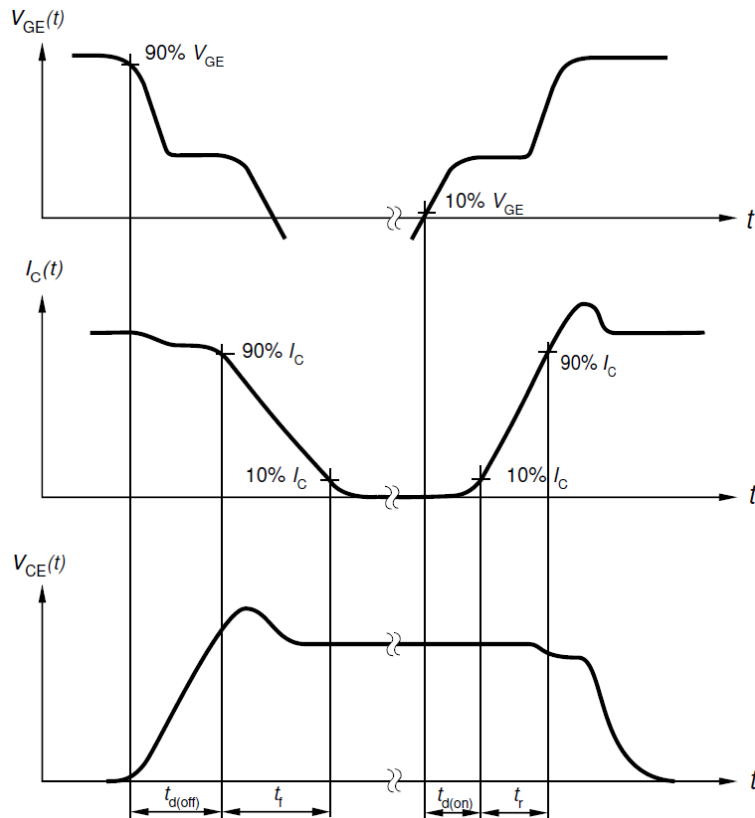
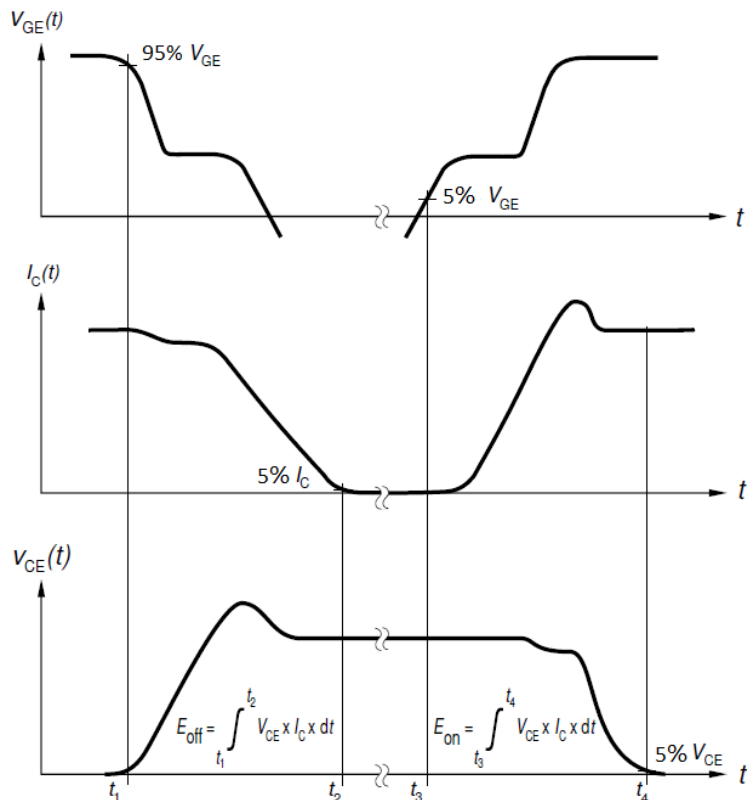
$$BV_{ces} = f(T_j);$$

Figure 16: Typical diode forward current as a function of forward voltage


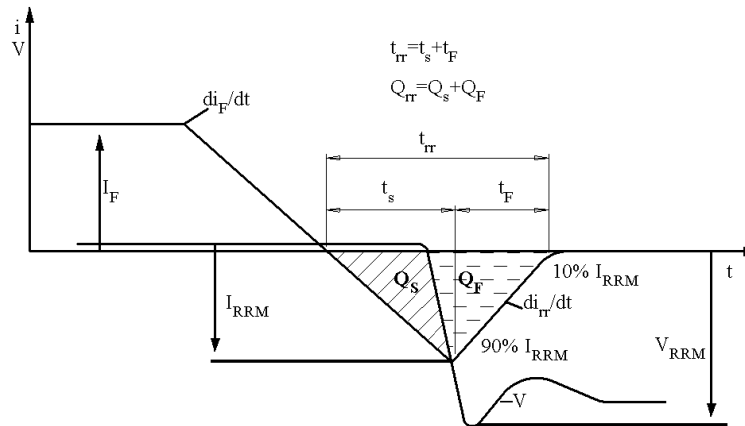
$$I_F = f(V_F);$$

Figure 17: Typical switching energy losses as a function of junction temperature


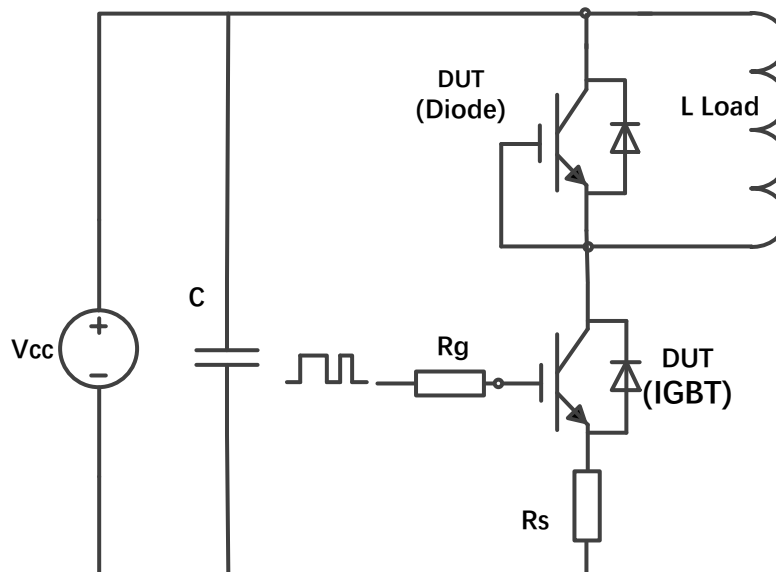
$$E = f(T_j); V_{CE} = 400V; I_C = 100A; R_G = 15\Omega$$

Test Circuits
1. Definition Switching times

2. Definition Switching losses


3. Definition Diode Switching Characteristics



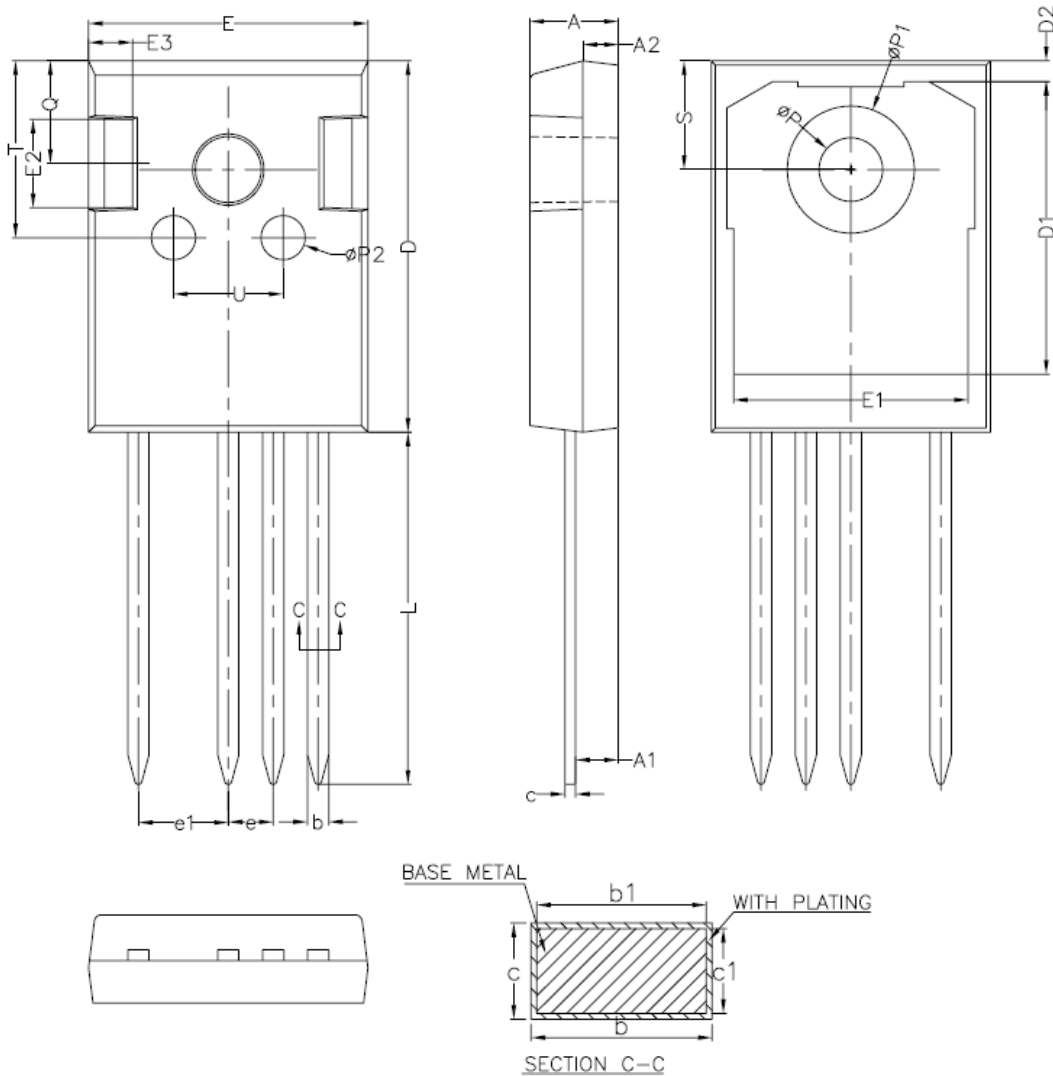
4. Dynamic Test Circuit



Mechanical Dimensions

TO-247-4

Unit: mm



100A 650V Trench Fieldstop IGBT with anti-parallel diode SRE100N065FSUD8
Mechanical Dimensions

mbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16	-	1.29
b1	1.15	1.2	1.25
c	0.59	-	0.66
c1	0.58	0.60	0.62
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.20	1.35
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	2.44	2.54	2.64
e1	4.98	5.08	5.18
L	19.80	19.92	20.10
P	3.50	3.60	3.70
P1	-	-	7.40
P2	2.40	2.50	2.60
Q	5.60	-	6.00
S	6.15 BSC		
T	9.80	-	10.20
U	6.00	-	6.40



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Main Site:

- Headquarter

Shenzhen Sanrise Technology Co., LTD.
A1206, Skyworth building, No. 008, gaoxinnan 1st Road,
Gaoxin District, Yuehai street, Nanshan District, ShenZhen,
P.R. China
Tel: +86-755-22953335
Fax: +86-755-22916878

- Shanghai Office

Shenzhen Sanrise Technology Co., LTD.
Rm.401, Building B, No. 666, Zhangheng Road,
Zhangjiang Hi-Tech Park, Shanghai, P.R.China
Tel: +86-21-68825918